

[54] **METHOD FOR PRODUCING AN IDENTIFICATION CARD WITH AN INTEGRATED CIRCUIT**

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- [63] Continuation of Ser. No. 562,217, Dec. 16, 1983, abandoned.

[30] **Foreign Application Priority Data**

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[52] **U.S. Cl.** 156/244.12; 29/827; 29/841; 156/293; 156/295; 264/272.17
[58] **Field of Search** 156/145, 146, 244.12, 156/293, 295, 303.1, 299; 283/83, 904; 29/841, 827; 264/272.17, 279.1; 357/72; 235/492, 488; 427/96; 40/630, 625

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[57] **ABSTRACT**

A multilayer identification card containing an IC module in a cavity. The cavity is filled with a polymer with a consistency ranging from liquid to pasty before the card compound is laminated using pressure and heat. During lamination, the polymer completely fills in the cavity around the IC module, supported by the applied pressure. In the finished card, the polymer is cross-linked to form a solid, rubber-like mass, which protects the IC module in the cavity of the card.

5 Claims, 3 Drawing Sheets

